

PRODUCT NUMBER

77312-YXXLF

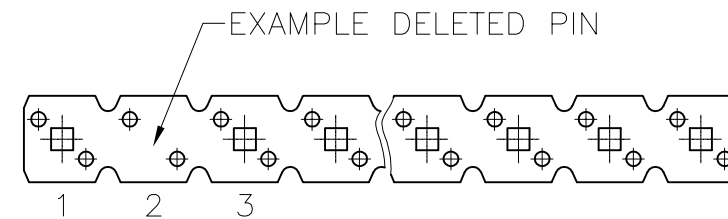
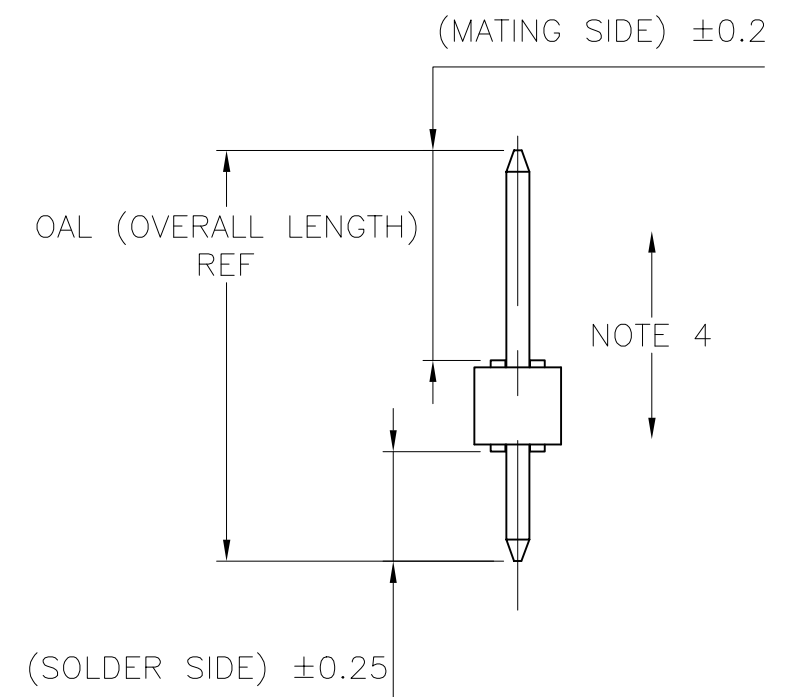
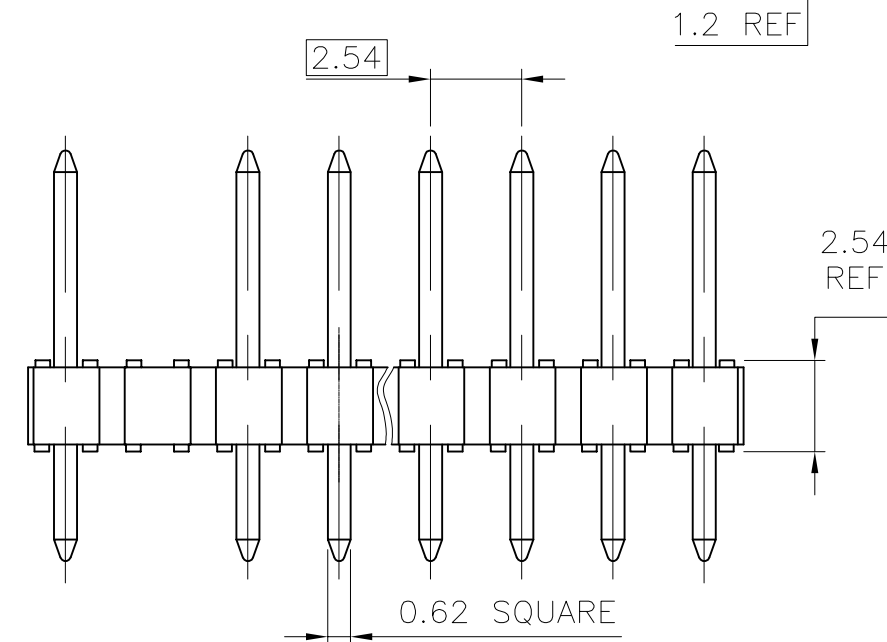
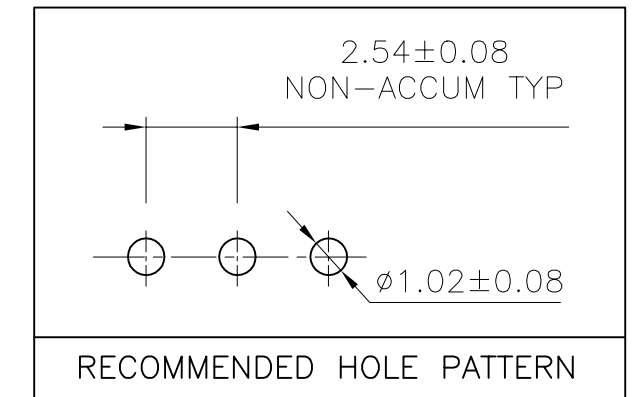
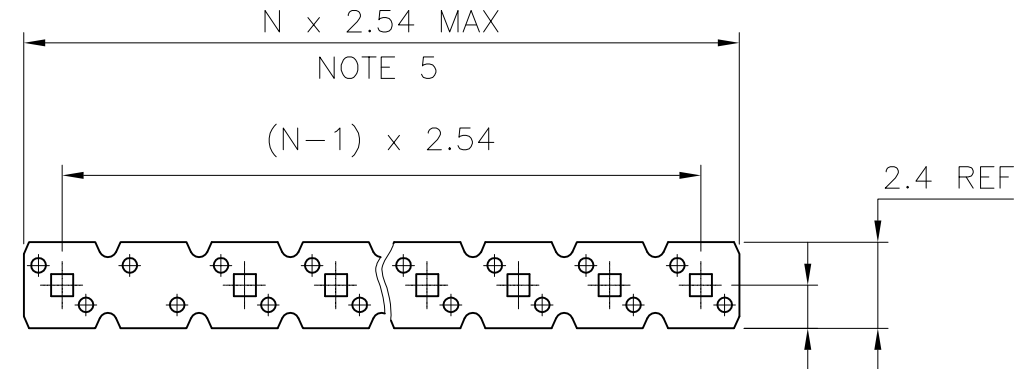
WHEN REQUIRED, ADD SUFFIX LETTER "LF"
INDICATES THE PRODUCT IS RoHS
COMPATIBLE, SEE NOTE 7

PIN STYLE

PLATING SEE SHEET 2

NOTES:

1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
2. PIN MATERIAL : PHOSPHOR BRONZE
3. PRODUCT PACKAGED IN POLY BAGS.
4. 9N MIN RETENTION IN EITHER DIRECTION
5. TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS N x 2.54 = 20.32mm
6. UNDERPLATING : 1.27µm Ni MIN
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
 - b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - d - LEGAL STATEMENT: SEE GS-22-008



BOTTOM VIEW

mat'l. code				surface		tolerance		projection		product family			
SEE NOTES				ISO 1302		ISO 406		ISO 1101		BSTIK			
ltr	ecn no	dr	date	tolerances unless		otherwise specified		mm		title			
AA	F04-0167	JCO	04.04.05	angles		linear		scale 5:1		HEADER SR,STR,			
AB	F04-0362	LMU	04.11.27							POL,DUPLEX,2.54mm			
AC	F06-0196	LMU	06.06.20							dwg no			
AD	F08-0148	RTR	08.03.31	dr		COMPAGNON J		95.10.27		sheet 1 of 4			
				enr		JMC		95.10.27		size			
X	F10707	LMU	01.11.28	chr						77312			
Y	F04-0129	LMU	04.02.04	appd		JMC		95.10.27		A3			
sheet	revision	AD	P	M	U					type			
index	sheet	1	2	3	4					CUSTOMER Drawing			

PIN STYLE	PRODUCT DEFINITION			
	NB OF POS	MATING SIDE	SOLDER SIDE	("OAL") REF
01	1x 5	5.84	3.42	11.8
02	1x 8	5.84	3.42	11.8
03	1x 3	5.84	3.42	11.8
04	1x 8	5.72	2.54	10.8
05	1x 16	5.72	2.54	10.8
06	1x 12	5.72	2.54	10.8
07	1x 28	5.84	3.42	11.8
15	1x 19	5.84	3.42	11.8
16	1x 18	5.84	3.42	11.8
17	1x 7	5.84	3.42	11.8
18	1x 7	5.84	3.42	11.8
19	1x 9	5.84	3.42	11.8
20	1x 9	5.84	3.42	11.8
21	1x 32	5.84	3.42	11.8
22	1x 32	5.84	3.42	11.8

BOTTOM VIEW OF HEADER
SHOWING MISSING PIN POSITIONS

1 2 3

1 5 10 15 20 25 30 35

1 2 3 4 5 6 7 8 9 10 11 12 13 14

77312-8XXLF	0.38 μ m Au/GXT	2.0-7.5 μ m Sn MATTE
77312-4XXLF	2.0-7.5 μ m Sn MATTE	
77312-2XXLF	1.27 μ m Au	2.0-7.5 μ m Sn MATTE
77312-1XXLF	0.76 μ m Au/GXT	2.0-7.5 μ m Sn MATTE
77312-1XXSLF	0.76 μ m Au/GXT	GOLD FLASH

77312-8XX	0.38μm Au/GXT	4μm SnPb
77312-4XX	4μm SnPb FULL PLATED	
77312-2XX	1.27μm Au	4μm SnPb
77312-1XX	0.76μm Au/GXT	4μm SnPb
77312-1XXS	0.76μm Au/GXT	GOLD FLASH
PLATING CODE	CONTACT AREA	REMAINDER
	PLATING THICKNESS OVER 1.27μm Ni	

[illegible]

BOTTOM VIEW OF HEADER
SHOWING MISSING PIN POSITIONS

1 2 3

1 5 10 15 20 25 30

